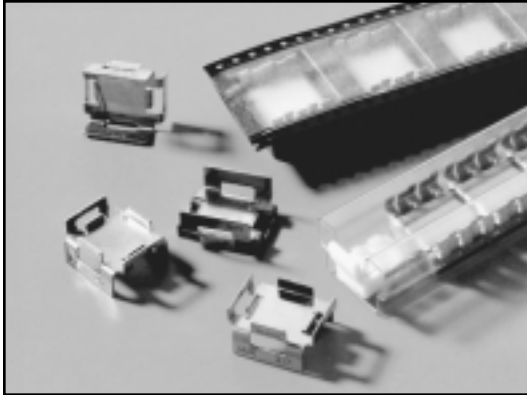


BOARD LEVEL POWER SEMICONDUCTOR HEAT SINKS



217 SERIES Surface Mount Heat Sinks

D²PAK, TO-220, SOT-223, SOL-20

Compatible with surface mount technology (SMT) automated production techniques for ease of assembly and a variety of soldering methods, these heat sinks allow greater packaging densities and reduction in PC-board area, increasing the power dissipation of surface mount devices (SMDs) while maintaining and improving manufacturers' component thermal specifications.

FEATURES AND BENEFITS:

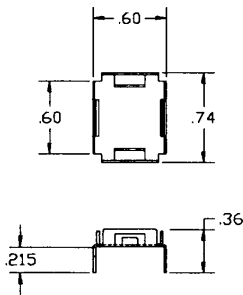
- No interface material is needed
- Copper with tin-lead plating for improved solderability and assembly
- Both the component and the heat sink are installed on the PC-board utilizing standard SMT assembly equipment for "Tape & Reel" and "Tube" formats
- EIA standards and ESD protection are specified
- Can be used with water soluble or no clean SMT solder creams or other pastes

Standard P/N	Height Above PC Board in. (mm)	Footprint Dimensions in. (mm)	Package Format	Package Quantity	Thermal Performance at Typical Load	
					Natural Convection	Forced Convection)
217-36CT6 ▲	.360 (9.1)	.600 (15.2) x .740 (18.8)	Bulk	1	55°C @ 1W	16.0°C/W @ 200 LFM
217-36CTT6	.360 (9.1)	.600 (15.2) x .740 (18.8)	Tube	20	55°C @ 1W	16.0°C/W @ 200 LFM
217-36CTR6▲	.360 (9.1)	.600 (15.2) x .740 (18.8)	Tape & Reel	250	55°C @ 1W	16.0°C/W @ 200 LFM

Material: Copper, Tin, Lead Plated

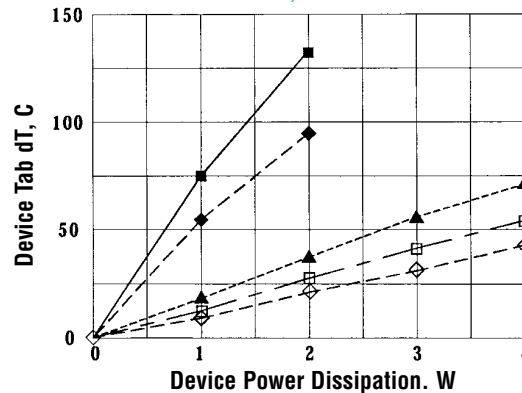
MECHANICAL DIMENSIONS

217 HEAT SINK WITH D²PAK DEVICE

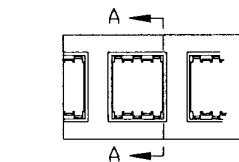


217-36CT6

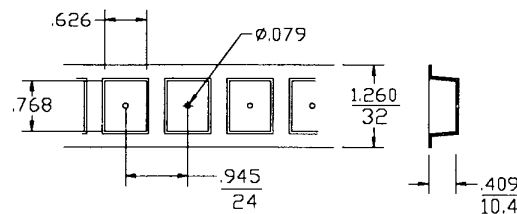
THERMAL PERFORMANCE 6 LAYER BOARD, D²PAK 125°C LEAD, 40°C AMBIENT



KEY: ■ Device only, NC ◆ Device + HS, NC ▲ Device + HS, 100 lfm □ Device + HS, 200 lfm ◇ Device + HS, 300 lfm



SECTION A-A

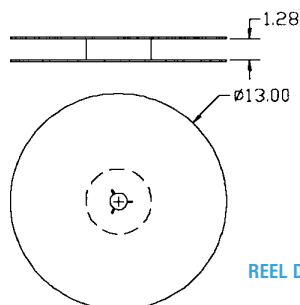


TAPE DETAILS

NOTES

1. Material to be "ESD"
2. Approximately 6 Meters per Reel
3. 250 Pieces per Reel.

217-36CTR6

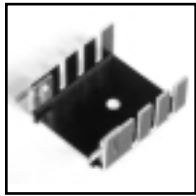


REEL DETAILS

Dimensions: in.

D²PAK, TO-220, SOL-20

BOARD LEVEL POWER SEMICONDUCTOR HEAT SINKS



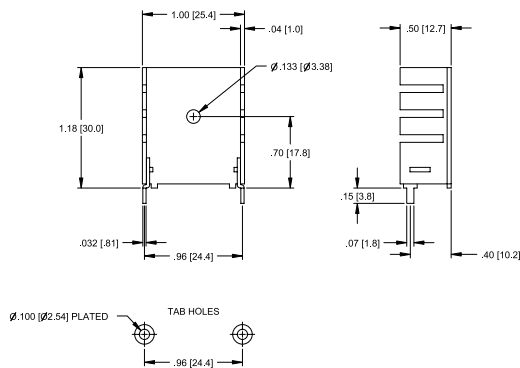
206 SERIES Vertical Mount Heat Sink

TO-220

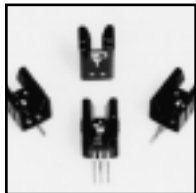
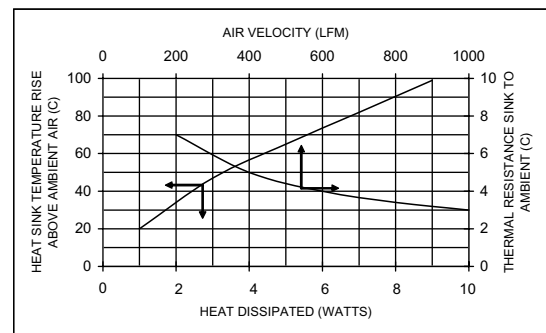
Standard P/N	Height Above PC Board	Maximum Footprint	Thermal Performance at Typical Load	
			Natural Convection	Forced Convection
206-1PABH	1.18" (30.0)	1.00" (25.4) x .50" (12.7)	56°C rise @ 4W	7.3°C/W @ 200LFM

Material: Aluminum, Black Anodized

MECHANICAL DIMENSIONS



NATURAL AND FORCED CONVECTION CHARACTERISTICS



PATENT PENDING

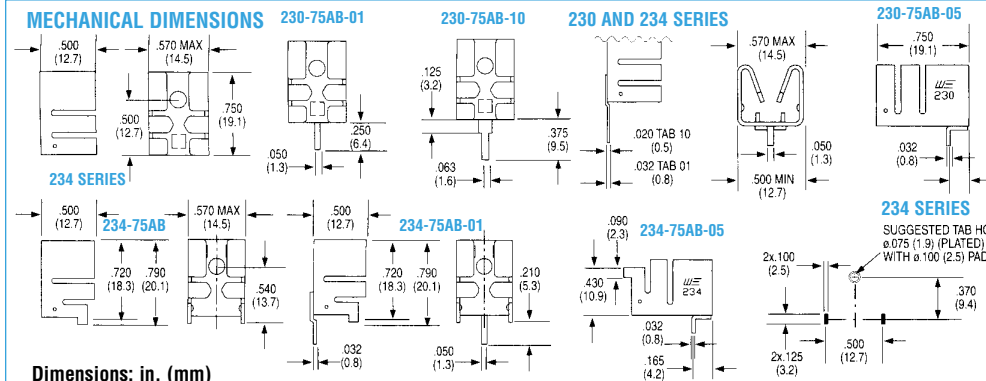
230 AND 234 SERIES Compact, Wavesolderable Low-Profile Self-Locking Heat Sinks

TO-220

Standard P/N	Height Above PC Board in. (mm)	Footprint Dimensions in. (mm)	Mounting Configuration	Solderable Tab Option	Mounting Style	Thermal Performance at Typical Load	
						Natural Convection	Forced Convection
230-75AB ▲	.750 (19.1)	.570 (14.5) x .500 (12.7)	Vert./Horiz.	No Tab	Clip/Mtg Hole	57°C @ 2W	7.5°C/W @ 400 LFM
230-75AB-01	.750 (19.1)	.570 (14.5) x .500 (12.7)	Vertical	01	Clip/Mtg Hole	57°C @ 2W	7.5°C/W @ 400 LFM
230-75AB-05	.500 (12.7)	.750 (19.1) x .570 (14.5)	Horizontal	05	Clip/Mtg Hole	57°C @ 2W	7.5°C/W @ 400 LFM
230-75AB-10	.875 (22.2)	.570 (14.5) x .500 (12.7)	Vertical	10	Clip/Mtg Hole	57°C @ 2W	7.5°C/W @ 400 LFM
234-75AB	.790 (20.0)	.570 (14.5) x .500 (12.7)	Vert./Horiz.	No Tab	Clip/Mtg Hole	57°C @ 2W	7.5°C/W @ 400 LFM
234-75AB-01	.790 (20.0)	.570 (14.5) x .500 (12.7)	Vertical	01	Clip/Mtg Hole	57°C @ 2W	7.5°C/W @ 400 LFM
234-75AB-05	.500 (12.7)	.790 (20.0) x .570 (14.5)	Horizontal	05	Clip/Mtg Hole	57°C @ 2W	7.5°C/W @ 400 LFM

Material: Aluminum, Black Anodized

MECHANICAL DIMENSIONS

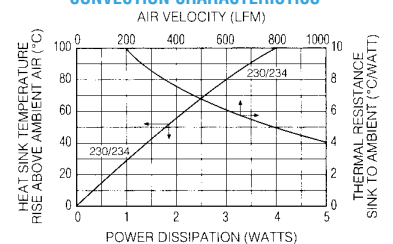


Dimensions: in. (mm)

230 SERIES

SUGGESTED TAB HOLE=
Ø.075 (1.9) (PLATED)
WITH Ø.100 (2.5) PAD

NATURAL AND FORCED CONVECTION CHARACTERISTICS



BOARD LEVEL POWER SEMICONDUCTOR HEAT SINKS



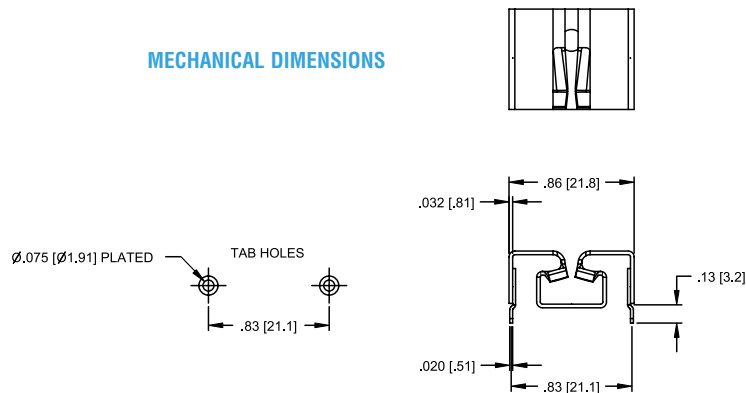
241 SERIES *Horizontal Mount Heat Sink*

TO-220

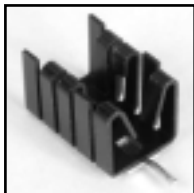
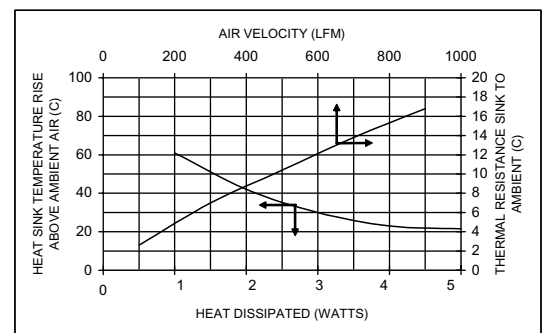
Standard P/N	Height Above PC Board	Maximum Footprint	Thermal Performance at Typical Load	
			Natural Convection	Forced Convection
241-69AB-03	.39" (9.9)	.86" (21.8) x .69" (17.5)	77°C rise @ 4W	12°C/W @ 200LFM

Material: Aluminum, Black Anodized

MECHANICAL DIMENSIONS



NATURAL AND FORCED CONVECTION CHARACTERISTICS



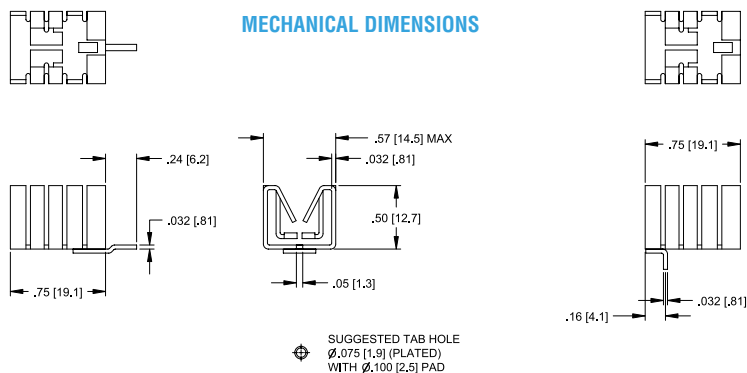
262 SERIES *Horizontal and Vertical Mount Heat Sink*

TO-220

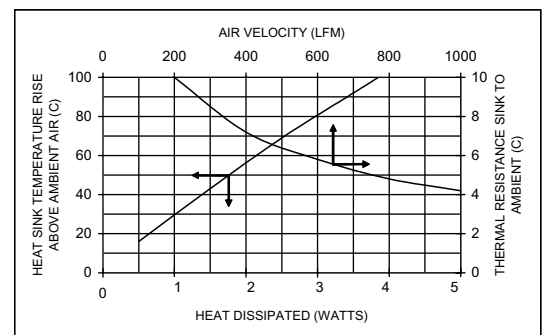
Standard P/N	Height Above PC Board	Maximum Footprint	Thermal Performance at Typical Load	
			Natural Convection	Forced Convection
262-75AB-05	.53" (13.4)	.75" (19.1) x .50" (12.7)	80°C rise @ 3W	10°C/W @ 200LFM
262-75AB-01	.75" (19.1)	.53" (13.4) x .50" (12.7)	80°C rise @ 3W	10°C/W @ 200LFM

Material: Aluminum, Black Anodized

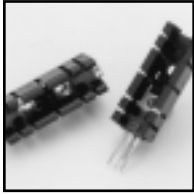
MECHANICAL DIMENSIONS



NATURAL AND FORCED CONVECTION CHARACTERISTICS



BOARD LEVEL POWER SEMICONDUCTOR HEAT SINKS



PATENT PENDING

233 AND 236 SERIES

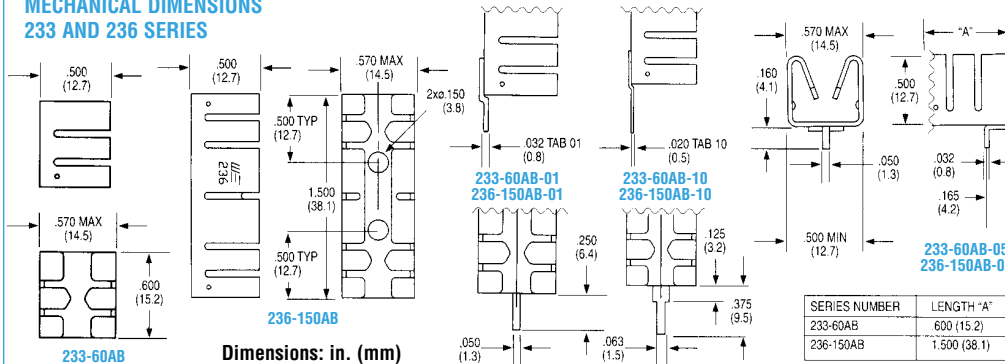
Self-Locking Wavesolderable Heat Sinks

TO-220

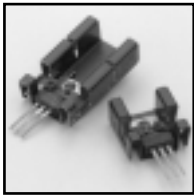
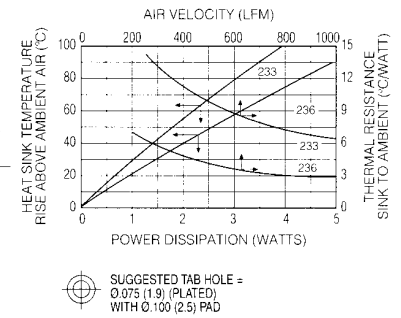
Standard P/N	Height Above PC Board in. (mm)	Footprint Dimensions in. (mm)	Mounting Configuration	Solderable Tab Options	Mounting Style	Thermal Performance at Typical Load Natural Convection	Thermal Performance at Typical Load Forced Convection
233-60AB ▲	.600 (15.2)	.570 (14.5) x .500 (12.7)	Vert./Horiz.	No Tab	Clip/Mtg Hole	58°C @ 2W	11.0°C/W @ 400 LFM
233-60AB-01	.600 (15.2)	.570 (14.5) x .500 (12.7)	Vertical	01	Clip/Mtg Hole	58°C @ 2W	11.0°C/W @ 400 LFM
233-60AB-05	.500 (12.7)	.600 (15.2) x .570 (14.5)	Horizontal	05	Clip/Mtg Hole	58°C @ 2W	11.0°C/W @ 400 LFM
233-60AB-10 ▲	.725 (18.4)	.570 (14.5) x .500 (12.7)	Vertical	10	Clip/Mtg Hole	58°C @ 2W	11.0°C/W @ 400 LFM
236-150AB	1.500 (38.1)	.570 (14.5) x .500 (12.7)	Vert./Horiz.	No Tab	Clip/Mtg Hole	58°C @ 2W	4.80°C/W @ 400 LFM
236-150AB-01	1.500 (38.1)	.570 (14.5) x .500 (12.7)	Vertical	01	Clip/Mtg Hole	58°C @ 2W	4.80°C/W @ 400 LFM
236-150AB-05 ▲	.500 (12.7)	1.500 (38.1) x .570 (14.5)	Horizontal	05	Clip/Mtg Hole	58°C @ 2W	4.80°C/W @ 400 LFM
236-150AB-10	1.625 (41.3)	.570 (14.5) x .570 (12.7)	Vertical	10	Clip/Mtg Hole	58°C @ 2W	4.80°C/W @ 400 LFM

Material: Aluminum, Black Anodized

MECHANICAL DIMENSIONS 233 AND 236 SERIES



NATURAL AND FORCED CONVECTION CHARACTERISTICS



PATENT 5381041

275 AND 231 SERIES

Compact, Stress-Free Labor-Saving Locking-Tab Heat Sinks

TO-220

Standard P/N	Height Above PC Board in. (mm)	Footprint Dimensions in. (mm)	Mounting Configuration	Solderable Tab Options	Mounting Style	Thermal Performance at Typical Load Natural Convection	Thermal Performance at Typical Load Forced Convection
275-75AB	.750 (19.1)	.835 (21.2) x .400 (12.7)	Vert./Horiz.	No Tab	Clip/Mtg Hole	44°C @ 2W	7.9°C/W @ 400 LFM
275-75AB-01	.750 (19.1)	.835 (21.2) x .400 (12.7)	Vertical	01	Clip/Mtg Hole	44°C @ 2W	7.9°C/W @ 400 LFM
275-75AB-10	.875 (12.7)	.835 (21.2) x .400 (14.5)	Vertical	10	Clip/Mtg Hole	44°C @ 2W	7.9°C/W @ 400 LFM
231-69PAB	.690 (18.4)	.835 (21.2) x .400 (12.7)	Vert./Horiz.	No Tab	Clip/Mtg Hole	45°C @ 2W	8°C/W @ 400 LFM
231-69PAB-13H	.400 (38.1)	.690 (17.5) x .835 (12.7)	Horizontal	13H	Clip/Mtg Hole	45°C @ 2W	8°C/W @ 400 LFM
231-69PAB-XXX	.690 (38.1)	.835 (21.2) x .400 (12.7)	Vertical	13V, 14V, 15V	Clip/Mtg Hole	45°C @ 2W	8°C/W @ 400 LFM
231-75PAB	.750 (12.7)	.835 (21.2) x .400 (14.5)	Vert./Horiz.	No Tab	Clip/Mtg Hole	43°C @ 2W	7.9°C/W @ 400 LFM
231-75PAB-13H	.400 (41.3)	.750 (19.1) x .835 (12.7)	Horizontal	13H	Clip/Mtg Hole	43°C @ 2W	7.9°C/W @ 400 LFM
(14V) 231-75PAB-XXX	.750 (34.9)	.835 (21.2) x .400 (12.7)	Vertical	13V, 14V, 15V	Clip/Mtg Hole	43°C @ 2W	7.9°C/W @ 400 LFM
231-137PAB	1.375 (10.2)	.835 (21.2) x .400 (12.7)	Vert./Horiz.	No Tab	Clip/Mtg Hole	32°C @ 2W	5.9°C/W @ 400 LFM
231-137PAB-13H	.400 (10.2)	1.375 (34.9) x .835 (12.7)	Horizontal	13H	Clip/Mtg Hole	32°C @ 2W	5.9°C/W @ 400 LFM
(15V) 231-137PAB-XXX	1.375 (10.2)	.835 (21.2) x .400 (12.7)	Vertical	13V, 14V, 15V	Clip/Mtg Hole	32°C @ 2W	5.9°C/W @ 400 LFM

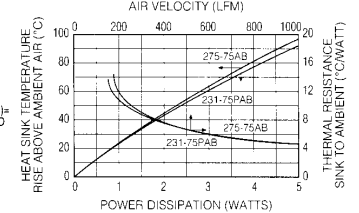
Material: Aluminum, Pre-anodized Black (PAB), Anodized Black (AB)

MECHANICAL DIMENSIONS

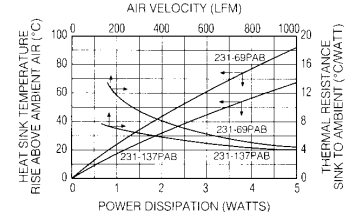
Dimple on 231-69, 275-75 Series only

275 AND 231 SERIES

NATURAL AND FORCED CONVECTION CHARACTERISTICS



NATURAL AND FORCED CONVECTION CHARACTERISTICS



All versions No Tab

Dimensions: in. (mm)

BOARD LEVEL POWER SEMICONDUCTOR HEAT SINKS



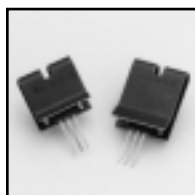
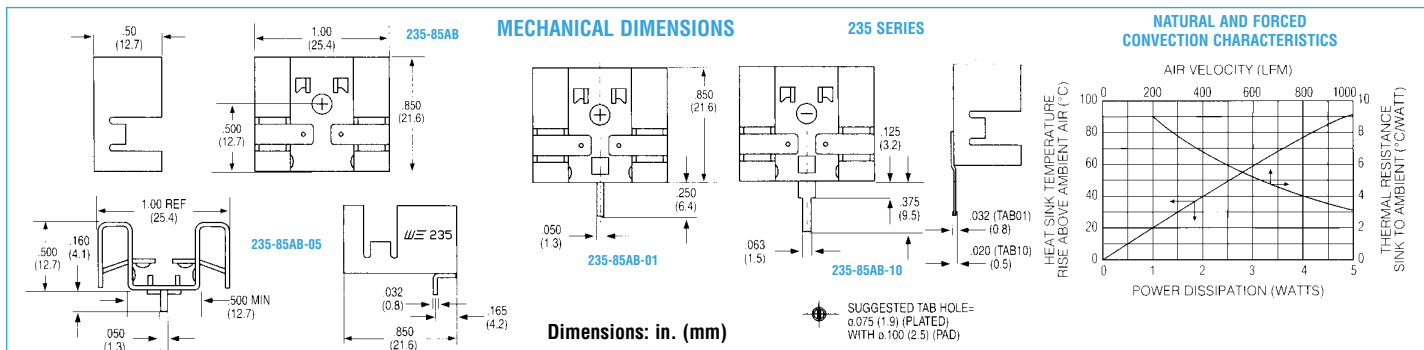
PATENT 5381041

235 SERIES Compact, Stress-Free Labor-Saving Locking-Tab Heat Sinks

TO-220

Standard P/N	Height Above PC Board in. (mm)	Footprint Dimensions in. (mm)	Mounting Configuration	Solderable Tab Options	Mounting Style	Thermal Performance at Typical Load Natural Convection	Thermal Performance at Typical Load Forced Convection
235-85AB ▲	.850 (21.6)	1.000 (25.4) x .500 (12.7)	Vert./Horiz.	No Tab	Clip/Mtg Hole	40°C @ 2W	6.8°C/W @ 400 LFM
235-85AB-01	.850 (21.6)	1.000 (25.4) x .500 (12.7)	Vertical	01	Clip/Mtg Hole	40°C @ 2W	6.8°C/W @ 400 LFM
235-85AB-05	.500 (12.7)	.850 (21.6) x 1.000 (25.4)	Horizontal	05	Clip/Mtg Hole	40°C @ 2W	6.8°C/W @ 400 LFM
235-85AB-10	.975 (24.8)	1.000 (25.4) x .500 (12.7)	Vertical	10	Clip/Mtg Hole	40°C @ 2W	6.8°C/W @ 400 LFM

Material: Aluminum, Black Anodized

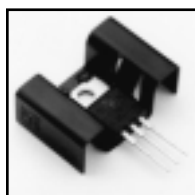
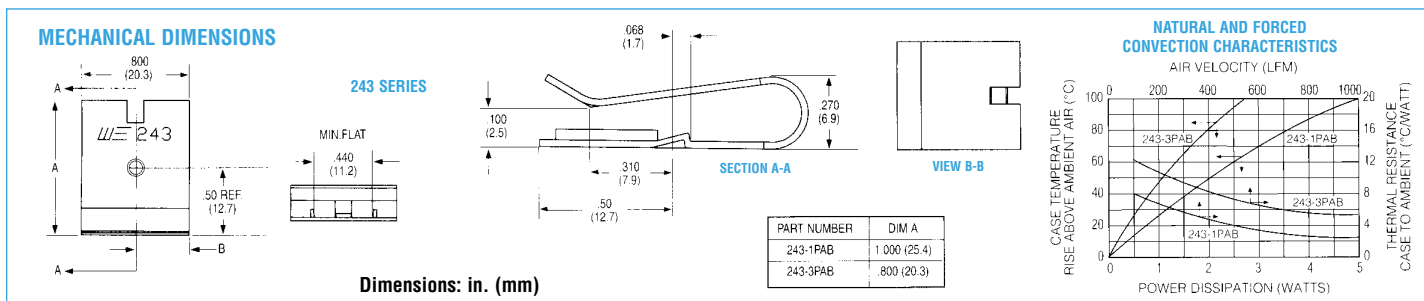


243 SERIES Labor-Saving Clip-On Heat Sinks

TO-220

Standard P/N	Height Above PC Board in. (mm)	Footprint Dimensions in. (mm)	Mounting Configuration	Solderable Tab Options	Mounting Style	Thermal Performance at Typical Load Natural Convection	Thermal Performance at Typical Load Forced Convection
243-1PAB	1.000 (25.4)	.800 (20.3) x .270 (6.9)	Vert./Horiz.	No Tab	Clip	50°C @ 2W	4.5°C/W @ 400 LFM
243-3PAB ▲	.800 (20.3)	.800 (20.3) x .270 (6.9)	Vert./Horiz.	No Tab	Clip	78°C @ 2W	8.2°C/W @ 400 LFM

Material: Aluminum, Pre-anodized Black



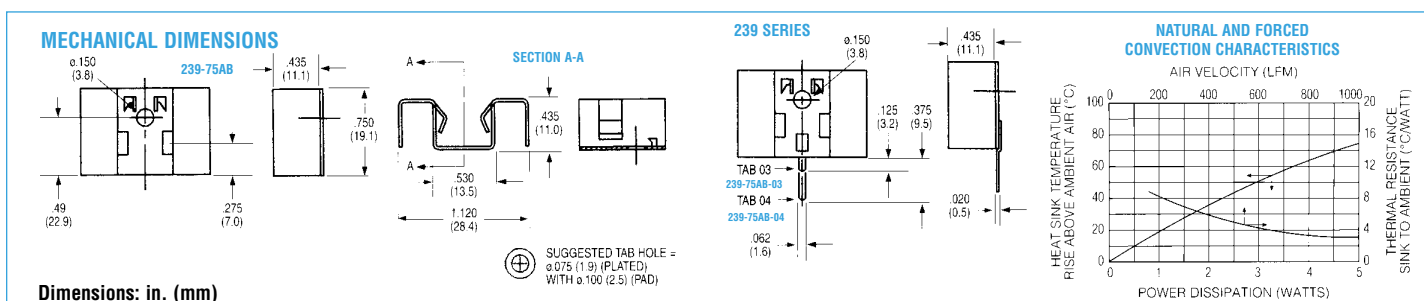
PATENT PENDING

239 SERIES Snap-Down Self-Locking Heat Sinks

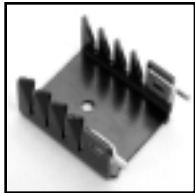
TO-220

Standard P/N	Height Above PC Board in. (mm)	Footprint Dimensions in. (mm)	Mounting Configuration	Solderable Tab Options	Mounting Style	Thermal Performance at Typical Load Natural Convection	Thermal Performance at Typical Load Forced Convection
239-75AB	.750 (19.1)	1.120 (28.4) x .435 (11.0)	Vert./Horiz	No Tab	Clip/Mtg Hole	38°C @ 2W	6°C/W @ 400 LFM
239-75AB-03	.750 (19.1)	1.120 (28.4) x .435 (11.0)	Vertical	03	Clip/Mtg Hole	38°C @ 2W	6°C/W @ 400 LFM
239-75AB-04	.750 (19.1)	1.120 (28.4) x .435 (11.0)	Vertical	04	Clip/Mtg Hole	38°C @ 2W	6°C/W @ 400 LFM

Material: Aluminum, Black Anodized



BOARD LEVEL POWER SEMICONDUCTOR HEAT SINKS



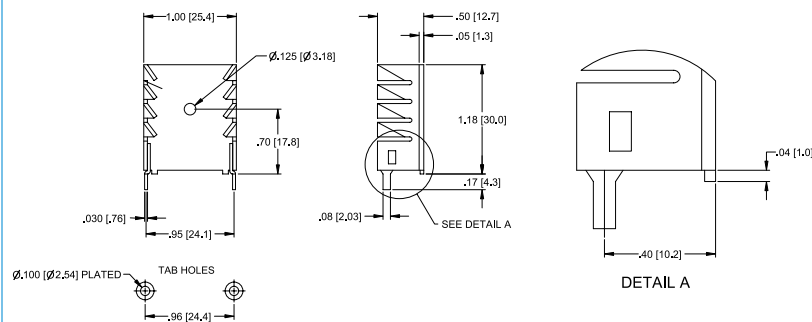
265 SERIES Vertical Mount Heat Sink

TO-220

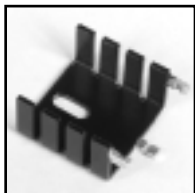
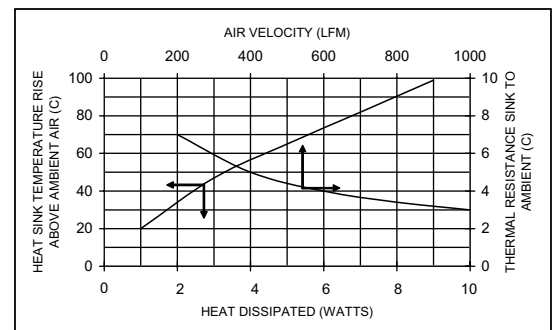
Standard PIN	Height Above PC Board	Maximum Footprint	Thermal Performance at Typical Load	
			Natural Convection	Forced Convection
265-118ABH-22	1.18" (30.0)	1.00" (25.4) x .50" (12.7)	56°C rise @ 4W	7.0°C/W @ 200LFM

Material: Aluminum, Black Anodized

MECHANICAL DIMENSIONS



NATURAL AND FORCED CONVECTION CHARACTERISTICS



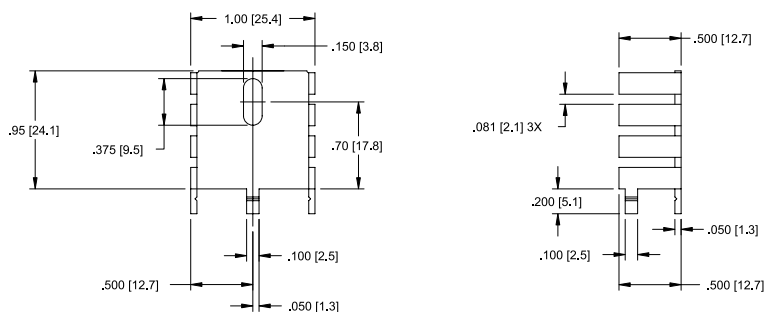
286DB SERIES Vertical Mount Heat Sink

TO-220

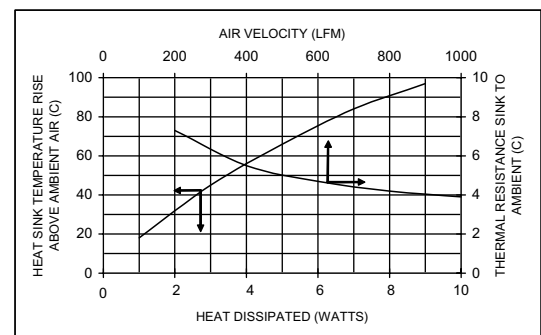
Standard PIN	Height Above PC Board	Maximum Footprint	Thermal Performance at Typical Load	
			Natural Convection	Forced Convection
286DB	.95" (24.1)	1.00" (25.4) x .50" (12.7)	65°C rise @ 4W	9.0°C/W @ 200LFM

Material: Aluminum, Black Anodized

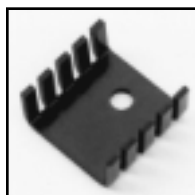
MECHANICAL DIMENSIONS



NATURAL AND FORCED CONVECTION CHARACTERISTICS



BOARD LEVEL POWER SEMICONDUCTOR HEAT SINKS



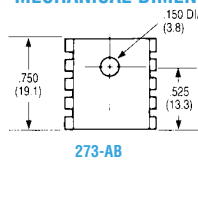
273 SERIES Low-Cost, Low-Height Wavesolderable Heat Sinks

TO-218, TO-220

Standard P/N	Height Above PC Board in. (mm)	Footprint Dimensions in. (mm)	Mounting Configuration	Solderable Tab Options	Mounting Style	Thermal Performance at Typical Load Natural Convection	Thermal Performance at Typical Load Forced Convection
273-AB ▲	.375 (9.5)	.750 (19.1) x .750 (19.1)	Vert./Horiz.	No Tab	Mtg Hole	49°C @ 2W	7.2°C/W @ 400 LFM
273-AB-01	.375 (9.5)	.750 (19.1) x .750 (19.1)	Vertical	01	Mtg Hole	49°C @ 2W	7.2°C/W @ 400 LFM
273-AB-02	.375 (9.5)	.750 (19.1) x .750 (19.1)	Vertical	02	Mtg Hole	49°C @ 2W	7.2°C/W @ 400 LFM

Material: Aluminum, Black Anodized

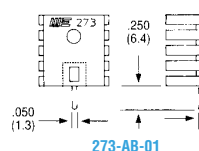
MECHANICAL DIMENSIONS



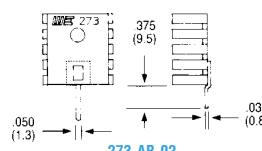
Note:

1. Suggested Tab Hole = ϕ .075 (1.9) (Plated) with ϕ .100 (2.5) pad

273 SERIES



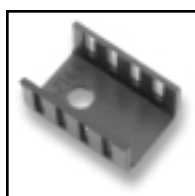
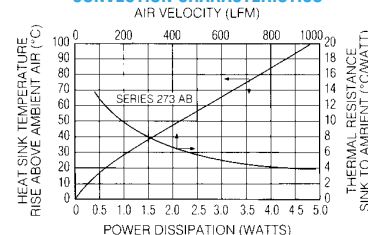
273-AB-01



273-AB-02

Dimensions: in. (mm)

NATURAL AND FORCED CONVECTION CHARACTERISTICS



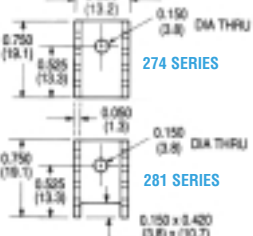
274 SERIES Low-Cost, Low-Height Wavesolderable Heat Sinks

TO-220

Standard P/N	Height Above PC Board in. (mm)	Footprint Dimensions in. (mm)	Mounting Configuration	Solderable Tab Options	Mounting Style	Thermal Performance at Typical Load Natural Convection	Thermal Performance at Typical Load Forced Convection
274-1AB ▲	.375 (9.5)	.520 (13.2) x .750 (19.1)	Vert./Horiz.	No Tab	Mtg Hole	56°C @ 2W	8.0°C/W @ 400 LFM
274-1AB-01 ▲	.375 (9.5)	.520 (13.2) x .750 (19.1)	Vertical	01	Mtg Hole	56°C @ 2W	8.0°C/W @ 400 LFM
274-1AB-02	.375 (9.5)	.520 (13.2) x .750 (19.1)	Vertical	02	Mtg Hole	56°C @ 2W	8.0°C/W @ 400 LFM
274-2AB ▲	.500 (12.7)	.520 (13.2) x .750 (19.1)	Vert./Horiz.	No Tab	Mtg Hole	50°C @ 2W	7.0°C/W @ 400 LFM
274-2AB-01	.500 (12.7)	.520 (13.2) x .750 (19.1)	Vertical	01	Mtg Hole	50°C @ 2W	7.0°C/W @ 400 LFM
274-2AB-02	.500 (12.7)	.520 (13.2) x .750 (19.1)	Vertical	02	Mtg Hole	50°C @ 2W	7.0°C/W @ 400 LFM
274-3AB ▲	.250 (6.4)	.520 (13.2) x .750 (19.1)	Vert./Horiz.	No Tab	Mtg Hole	62°C @ 2W	9.0°C/W @ 400 LFM
274-3AB-01	.250 (6.4)	.520 (13.2) x .750 (19.1)	Vertical	01	Mtg Hole	62°C @ 2W	9.0°C/W @ 400 LFM
274-3AB-02	.250 (6.4)	.520 (13.2) x .750 (19.1)	Vertical	02	Mtg Hole	62°C @ 2W	9.0°C/W @ 400 LFM
281-1AB	.375 (9.5)	.520 (13.2) x .750 (19.1)	Vertical	No Tab	Mtg Hole	56°C @ 2W	8.0°C/W @ 400 LFM
281-2AB	.500 (12.7)	.520 (13.2) x .750 (19.1)	Vertical	No Tab	Mtg Hole	50°C @ 2W	7.0°C/W @ 400 LFM

Material: Aluminum, Black Anodized

MECHANICAL DIMENSIONS

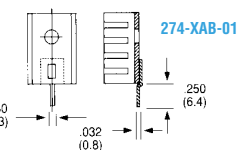
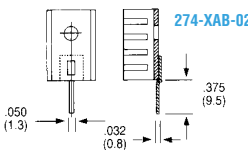


274 SERIES

281 SERIES

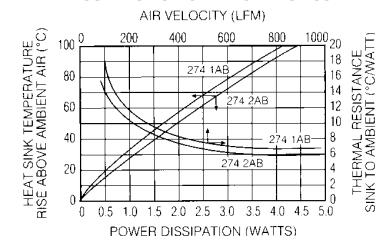
Dimensions: in. (mm)

274 SERIES


 ϕ .075 (1.9) (plated) ϕ .100 (2.5) pad
PCB recommended hole/pad size


274-XAB-02

NATURAL AND FORCED CONVECTION CHARACTERISTICS



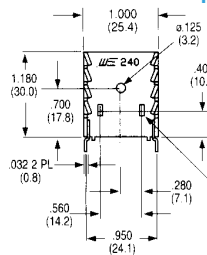
240 SERIES Labor-Saving Twisted Fin Heat Sinks

TO-220

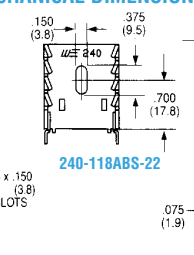
Standard P/N	Height Above PC Board in. (mm)	Footprint Dimensions in. (mm)	Mounting Configuration	Solderable Tab Options	Mounting Style	Thermal Performance at Typical Load Natural Convection	Thermal Performance at Typical Load Forced Convection
240-118ABH-22 ▲	1.180 (30.0)	1.000 (25.4) x .500 (12.7)	Vertical	22	Clip/Mtg Hole	55°C @ 4W	5.3°C/W @ 400 LFM
240-118ABS-22	1.180 (30.0)	1.000 (25.4) x .500 (12.7)	Vertical	22	Clip/Mtg Slot	55°C @ 4W	5.3°C/W @ 400 LFM

Material: Aluminum, Black Anodized

MECHANICAL DIMENSIONS



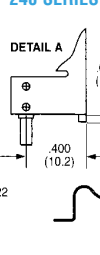
240-118ABH-22



240-118ABS-22

Dimensions: in. (mm)

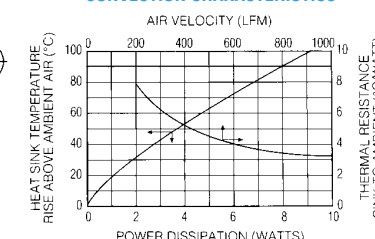
240 SERIES



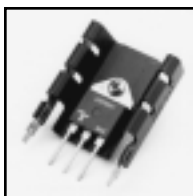
SPRING STEEL 285SC 10# STAINLESS STEEL 330SC 4#

Order SpeedClips™ Separately

NATURAL AND FORCED CONVECTION CHARACTERISTICS



BOARD LEVEL HEAT SINKS FOR TO-220, TO-218 AND MULTIWATT™ COMPONENTS



244 SERIES

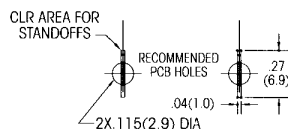
Low Height, Slim Profile Wiresolderable Folded Fin Heat Sinks

MULTIWATT

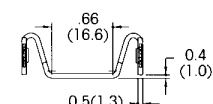
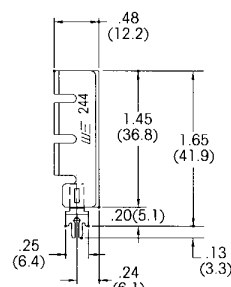
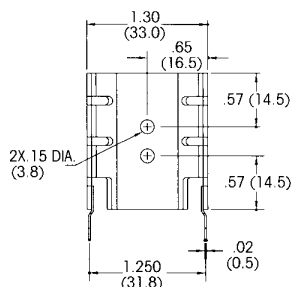
Standard P/N	Height Above PC Board in. (mm)	Footprint Dimensions in. (mm)	Mounting Configuration	Solderable Tab Options	Thermal Performance at Typical Load Natural Convection	Thermal Performance at Typical Load Forced Convection	Weight lbs. (grams)
244-145AB	1.450 (36.8)	1.300 (33.0) x .480 (12.1)	Vert./Horiz.	No Tab	44°C @ 4W	4.4°C/W @ 400 LFM	.0160 (7.25)
244-145AB-50	1.650 (41.9)	1.300 (33.0) x .480 (12.1)	Vertical	50	44°C @ 4W	4.4°C/W @ 400 LFM	.0170 (7.20)

Material: Aluminum, Black Anodized

MECHANICAL DIMENSIONS



Dimensions: in. (mm)



245 SERIES

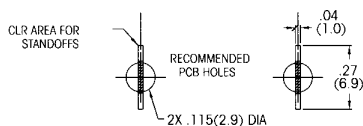
Low Height, Slim Profile Wiresolderable Folded Fin Heat Sinks

MULTIWATT

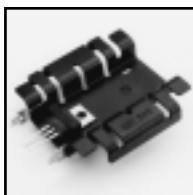
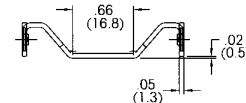
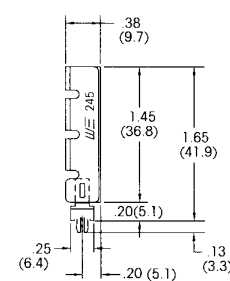
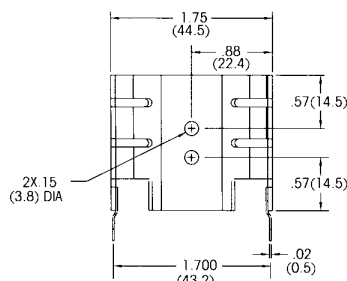
Standard P/N	Height Above PC Board in. (mm)	Footprint Dimensions in. (mm)	Mounting Configuration	Solderable Tab Options	Thermal Performance at Typical Load Natural Convection	Thermal Performance at Typical Load Forced Convection	Weight lbs. (grams)
245-145AB	1.450 (36.8)	1.750 (44.5) x .380 (9.7)	Vert./Horiz.	No Tab	38°C @ 4W	3.2°C/W @ 400 LFM	.0160 (7.25)
245-145AB-50	1.650 (41.9)	1.750 (44.5) x .380 (9.7)	Vertical	50	38°C @ 4W	3.2°C/W @ 400 LFM	.0170 (7.20)

Material: Aluminum, Black Anodized

MECHANICAL DIMENSIONS



Dimensions: in. (mm)



246 SERIES

Medium Height, Slim Profile Wiresolderable Folded Fin Heat Sinks

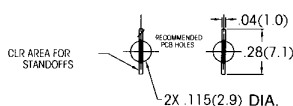
MULTIWATT

Standard P/N	Height Above PC Board in. (mm)	Footprint Dimensions in. (mm)	Mounting Configuration	Solderable Tab Options	Thermal Performance at Typical Load Natural Convection	Thermal Performance at Typical Load Forced Convection	Weight lbs. (grams)
246-197AB	1.968 (50.0)	1.986 (50.4) x 3.75 (9.5)	Vert./Horiz.	No Tab	35°C @ 4W	2.8°C/W @ 400 LFM	.0240 (10.90)
246-197AB-50	2.168 (55.1)	1.986 (50.4) x 3.75 (9.5)	Vertical	50	35°C @ 4W	2.8°C/W @ 400 LFM	.0250 (11.40)

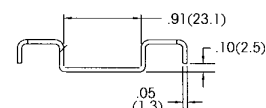
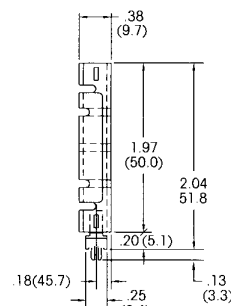
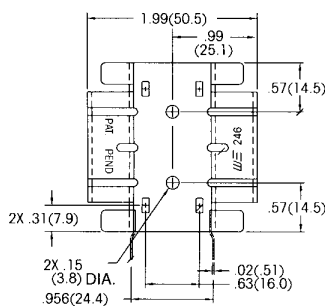
Order SpeedClip™ 285SC or 330SC separately. (See 248 Series section).

Material: Aluminum, Black Anodized

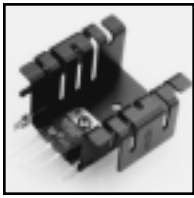
MECHANICAL DIMENSIONS



Dimensions: in. (mm)



BOARD LEVEL HEAT SINKS FOR TO-220, TO-218 AND MULTIWATT™ COMPONENTS



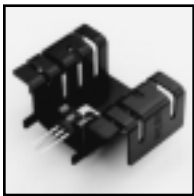
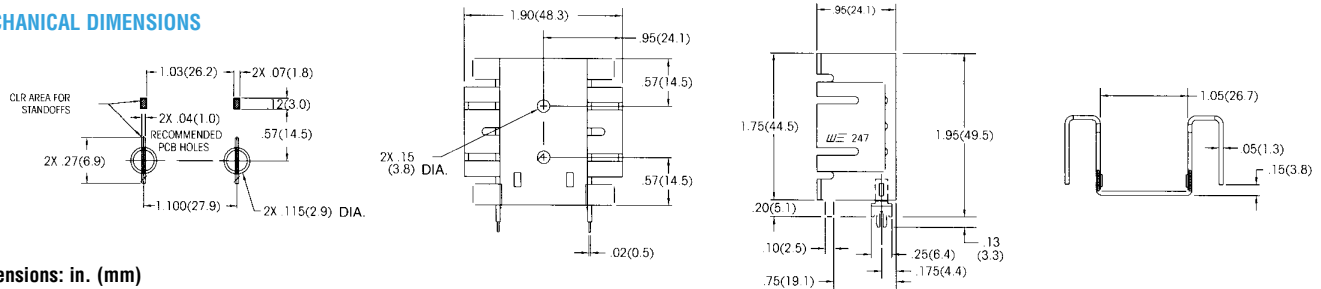
247 SERIES Medium Height, Deep Profile Wavesolderable Folded Fin Heat Sinks

MULTIWATT

Standard P/N	Height Above PC Board in. (mm)	Footprint Dimensions in. (mm)	Mounting Configuration	Solderable Tab Options	Thermal Performance at Typical Load		Weight lbs. (grams)
247-195AB	1.950 (49.5)	1.900 (48.3) x .950 (24.1)	Vert./Horiz.	No Tab	25°C@ 4W	2.4°C/W @ 400 LFM	.0330 (15.10)
247-195AB-50	1.950 (49.5)	1.900 (48.3) x .950 (24.1)	Vertical	50	25°C@ 4W	2.4°C/W @ 400 LFM	.0340 (15.60)

Order SpeedClip™ 285SC or 330SC separately. (See 248 Series section).
Material: Aluminum, Black Anodized

MECHANICAL DIMENSIONS



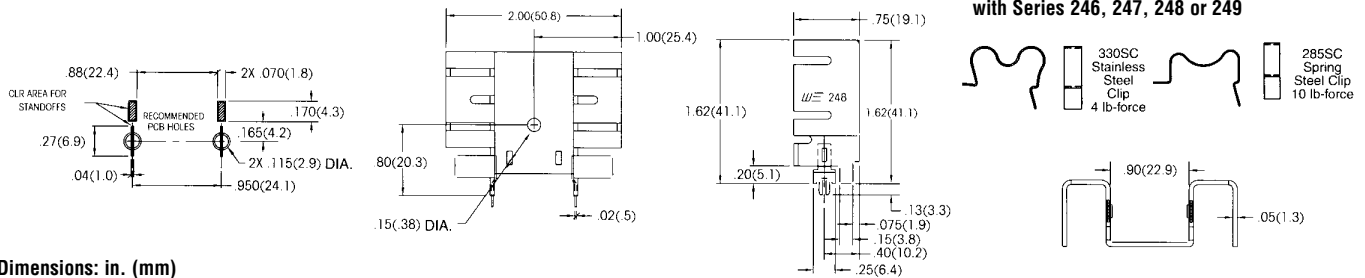
248 SERIES Low Height, Medium Profile Wavesolderable Folded Fin Heat Sinks

MULTIWATT

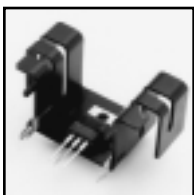
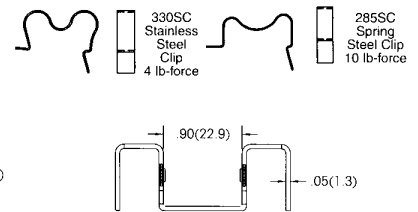
Standard P/N	Height Above PC Board in. (mm)	Footprint Dimensions in. (mm)	Mounting Configuration	Solderable Tab Options	Thermal Performance at Typical Load		Weight lbs. (grams)
248-162AB	1.620 (41.1)	2.000 (50.8) x .750 (19.1)	Vert./Horiz.	No Tab	35°C @ 4w	2.5°C/W @ 400 LFM	.026 (11.60)
248-162AB-50	1.620 (41.1)	2.000 (50.8) x .750 (19.1)	Vertical	50	35°C @ 4w	2.5°C/W @ 400 LFM	.027 (12.20)

Order SpeedClip™ 285SC or 330SC separately.
Material: Aluminum, Black Anodized

MECHANICAL DIMENSIONS



Order SpeedClips™ separately for use with Series 246, 247, 248 or 249



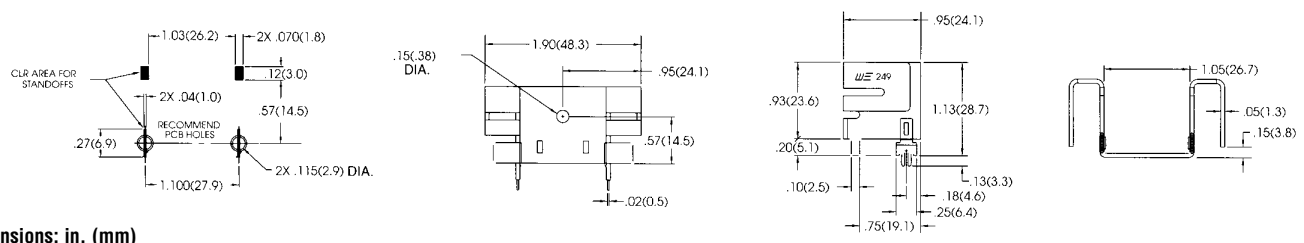
249 SERIES Medium Height, Deep Profile Wavesolderable Folded Fin Heat Sinks

MULTIWATT

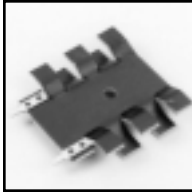
Standard P/N	Height Above PC Board in. (mm)	Footprint Dimensions in. (mm)	Mounting Configuration	Solderable Tab Options	Thermal Performance at Typical Load		Weight lbs. (grams)
249-113AB	1.130 (28.7)	1.900 (48.3) x .950 (24.1)	Vert./Horiz.	No Tab	35°C@ 4W	3.29°C/W @ 400 LFM	.020 (8.90)
249-113AB-50	1.130 (28.7)	1.900 (48.3) x .950 (24.1)	Vertical	50	35°C@ 4W	3.29°C/W @ 400 LFM	.021 (9.40)

Order SpeedClip™ 285SC or 330SC separately. (See 248 Series section).
Material: Aluminum, Black Anodized

MECHANICAL DIMENSIONS



BOARD LEVEL POWER SEMICONDUCTOR HEAT SINKS



288 SERIES Compact Wave-Solderable Low-Cost Heat Sinks

TO-220, TO-202

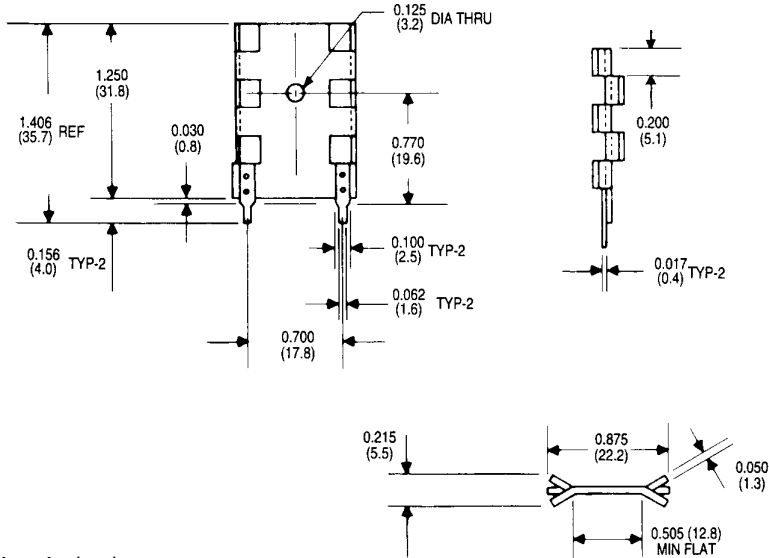
Standard P/N	Height Above PC Board in. (mm)	Maximum Footprint in. (mm)	Thermal Performance at Typical Load Natural Convection	Thermal Performance at Typical Load Forced Convection	Weight lbs. (grams)
288-1AB ▲	1.250 (31.8)	0.875 (22.2) x 0.215 (5.5)	85°C @ 4W	12°C/W @ 200 LFM	0.0057 (2.59)

Mounting tabs are pre-tinned to ensure excellent wave-solder bond and good electrical connections for vertical mounting of TO-220 and TO-202 semiconductor packages. These heat sinks are designed for use where minimum PC

board space is available. The 288-1AB is a stamped aluminum heat sink, black anodized, designed for applications requiring good heat dissipation from a heat sink occupying minimum space, available at minimum cost.

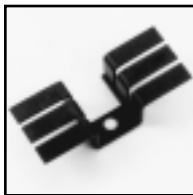
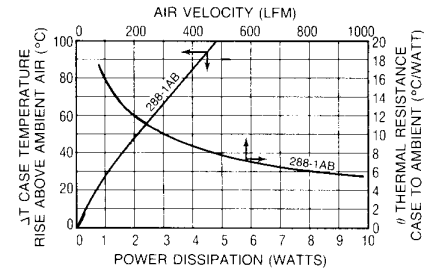
MECHANICAL DIMENSIONS

288 SERIES



Dimensions: in. (mm)

NATURAL AND FORCED CONVECTION CHARACTERISTICS



271 SERIES Top-Mount Booster Heat Sinks for Use with 270/272/280 Series

TO-220

Standard P/N	Height Above Semiconductor Case in. (mm)	Horizontal Mounting Footprint Dimensions in. (mm)	Thermal Performance at Typical Load Natural Convection	Thermal Performance at Typical Load Forced Convection	Weight lbs. (grams)
271-AB ▲	0.500 (12.7)	1.750 (44.5) x 0.700 (17.8)	62°C @ 4W (NOTE A) 31 °C @ 4W (NOTE B)	5.1°C/W @ 400 LFM 1.8°C/W 400 LFM (NOTE B)	0.0052 (2.36)

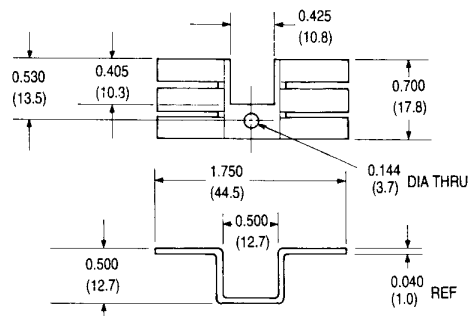
Material: Aluminum, Black Anodized

This top-hat style booster heat sink can be added to any of the 270, 272, or 280 Series for improved performance.

NOTE A: Thermal resistance with one 271-AB. NOTE B: Thermal resistance (total) as shown with (2) 271-AB types added to (1) 272-AB type.

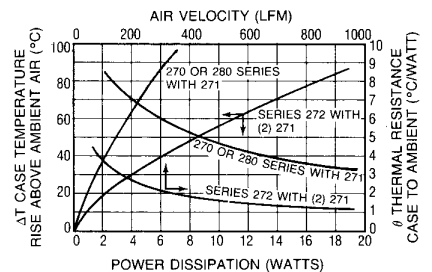
MECHANICAL DIMENSIONS

271 SERIES

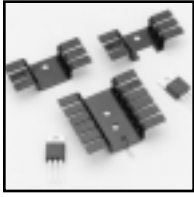


Dimensions: in. (mm)

NATURAL AND FORCED CONVECTION CHARACTERISTICS



BOARD LEVEL POWER SEMICONDUCTOR HEAT SINKS



270/272/280 SERIES Small Footprint Low-Cost Heat Sinks

TO-220, TO-202

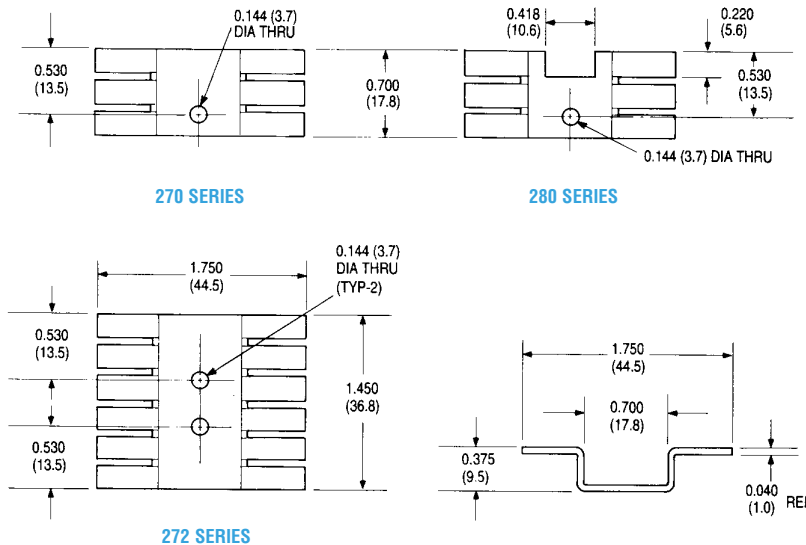
Standard P/N	Height Above PC Board in. (mm)	Horizontal Mounting Maximum Footing in. (mm)	Solderable Tab Options	Thermal Performance at Typical Load Natural Convection	Thermal Performance at Typical Load Forced Convection	Weight lbs. (grams)
270-AB ▲	0.375 (9.4)	1.750 (44.5) x 0.700 (17.8)	—	70°C @ 4W	6.0°C/W @ 400 LFM	0.0052 (2.36)
272-AB ▲	0.375 (9.4)	1.750 (44.5) x 1.450 (36.8)	01,02	42°C @ 4W	3.6°C/W @ 400 LFM	0.0105 (5.72)
280-AB	0.375 (9.4)	1.750 (44.5) x 0.700 (17.8)	—	70°C @ 4W	6.0°C/W @ 400 LFM	0.0048 (2.18)

Material: Aluminum, Black Anodized

These exceptionally low-cost heat sinks can be mounted horizontally under a TO-220 or TO-202 case style with a maximum height of only 0.375 in. (9.4). For added performance, a 271 Series heat sink can also be used for double-sided heat dissipation.

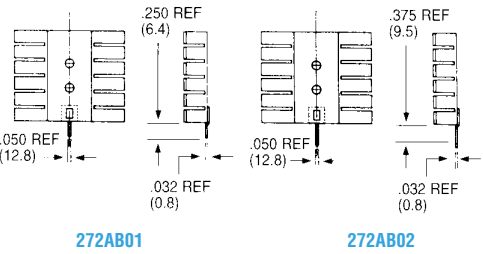
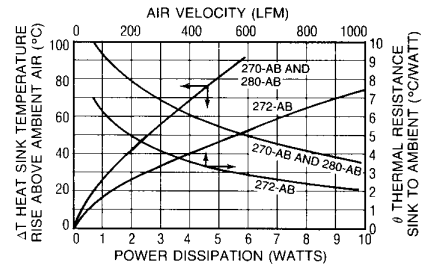
The 270-AB and 280-AB accept one power semiconductor; the 272-AB is designed for two power semiconductors. Specify solderable tab options for the 272 Series by the addition of suffix "01" or "02" to the standard part number (i.e. 272-AB01 or 272-AB02).

MECHANICAL DIMENSIONS



Dimensions: in. (mm)

NATURAL AND FORCED CONVECTION CHARACTERISTICS



Note:
1. Suggested Tab Hole = 0.075 ±0.003 plated with 0.100 pad



289 AND 290 SERIES Low-Cost Single or Dual Package Heat Sinks

TO-218, TO-202, TO-220

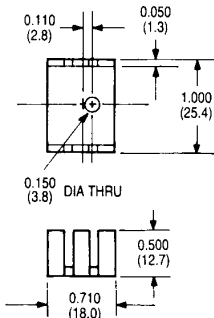
Standard P/N	Height Above PC Board in. (mm)	Horizontal Mounting Maximum Footing in. (mm)	Thermal Performance at Typical Load Natural Convection	Thermal Performance at Typical Load Forced Convection	Weight lbs. (grams)
289-AB ▲	0.500 (12.7)	1.000 (25.4) x 0.710 (18.1)	50°C @ 2W	9.0 C/W @ 400 LFM	0.0055 (2.49)
289-AP	0.500 (12.7)	1.000 (25.4) x 0.710 (18.1)	50°C @ 2W	9.0 C/W @ 400 LFM	0.0055 (2.49)
290-1AB ▲	0.500 (12.7)	1.000 (25.4) x 1.180 (30.0)	44°C @ 2W	7.0 C/W @ 400 LFM	0.0082 (3.72)
290-2AB ▲	0.500 (12.7)	1.000 (25.4) x 1.180 (30.0)	44°C @ 2W	7.0 C/W @ 400 LFM	0.0081 (3.67)

Material: Aluminum, Black Anodized

Low in cost and compact in overall dimensions, one 289 Series heat sink can accommodate one semiconductor; the 289 Series is available with a black anodized finish (289-AB) or with no finish (289-AP). Two semiconductors can be mounted to the 290-2AB style.

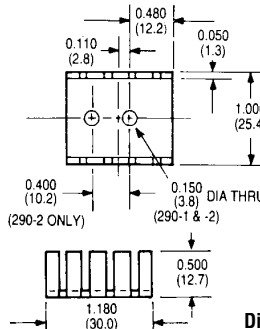
no finish (289-AP). Two semiconductors can be mounted to the 290-2AB style.

289 SERIES



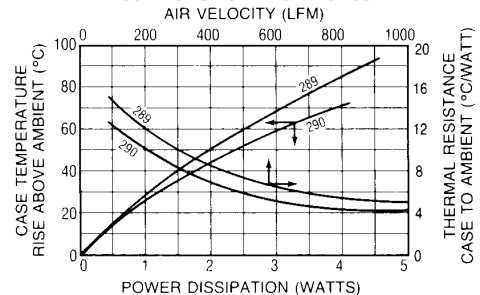
MECHANICAL DIMENSIONS

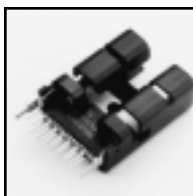
290 SERIES



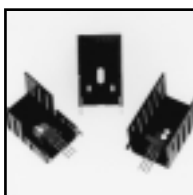
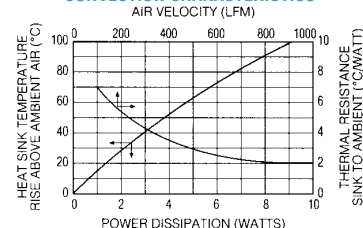
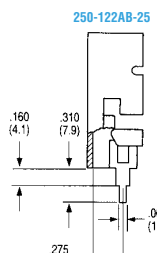
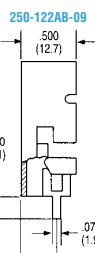
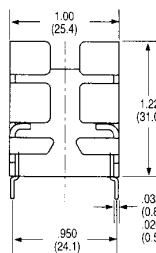
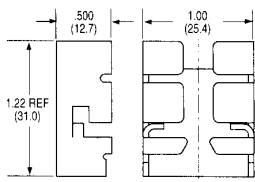
Dimensions: in. (mm)

NATURAL AND FORCED CONVECTION CHARACTERISTICS

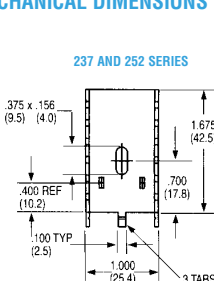




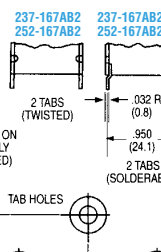
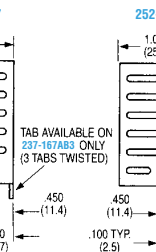
Standard P/N	Height Above PC Board in. (mm)	Footprint Dimensions in. (mm)	Mounting Configuration	Solderable Tab Options	Mounting Style	Thermal Performance at Typical Load	
						Natural Convection	Forced Convection
250-122AB	1.220 (31.0)	1.000 (25.4) x .500 (12.7)	Vert./Horiz.	No Tab	Clip	50°C @ 4W	3.7°C/W @ 400 LFM
250-122AB-09 ▲	1.220 (31.0)	1.000 (25.4) x .500 (12.7)	Vertical	09	Clip	50°C @ 4W	3.7°C/W @ 400 LFM
250-122AB-25	1.380 (35.1)	1.000 (25.4) x .500 (12.7)	Vertical	25	Clip	50°C @ 4W	3.7°C/W @ 400 LFM



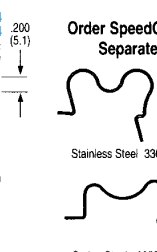
Standard P/N	Height Above PC Board in. (mm)	Footprint Dimensions in. (mm)	Mounting Configuration	Solderable Tab Options	Mounting Style	Thermal Performance at Typical Load	
						Natural Convection	Forced Convection
237-167AB2	1.675 (42.5)	1.000 (25.4) x 1.000 (25.4)	Vertical	2, Twisted	Clip/Mtg Slot	46°C @ 4W	4.5°C/W @ 200 LFM
237-167AB3	1.675 (42.5)	1.000 (25.4) x 1.000 (25.4)	Vertical	3, Twisted	Clip/Mtg Slot	46°C @ 4W	4.5°C/W @ 200 LFM
237-167AB2-24	1.675 (42.5)	1.000 (25.4) x 1.000 (25.4)	Vertical	2, Solderable	Clip/Mtg Slot	46°C @ 4W	4.5°C/W @ 200 LFM
252-167AB2	1.675 (42.5)	1.000 (25.4) x 1.000 (25.4)	Vertical	2, Twisted	Clip/Mtg Slot	40°C @ 4W	4.5°C/W @ 200 LFM
252-167AB3	1.675 (42.5)	1.000 (25.4) x 1.000 (25.4)	Vertical	3, Twisted	Clip/Mtg Slot	40°C @ 4W	4.5°C/W @ 200 LFM
252-167AB2-24	1.675 (42.5)	1.000 (25.4) x 1.000 (25.4)	Vertical	2, Solderable	Clip/Mtg Slot	40°C @ 4W	4.5°C/W @ 200 LFM



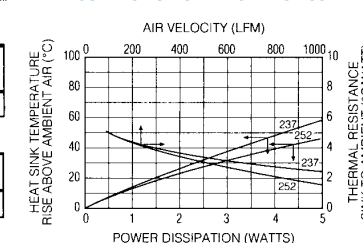
227-167



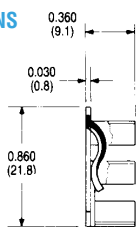
B2 237-167AB2



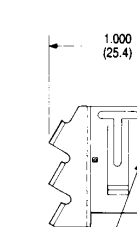
2015-2016



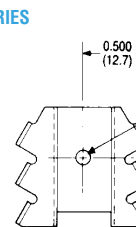
Standard P/N	Height Above PC Board in. (mm)	Vertical Mounting Footprint Dimensions in. (mm)	Mounting Style	Thermal Performance at Natural Convection	Typical Load Forced Convection	Weight lbs. (grams)
291-C236AB	0.860 (21.9)	1.100 (27.0) x 0.360 (9.1)	TO-220 (Clip)	80° C @ 2W	24° C/W @ 600 LFM	0.0026 (1.18)
291-H36AB ▲	0.860 (21.9)	1.100 (27.0) x 0.360 (9.1)	TO-220 (Mtg. Hole)	68° C @ 2W	16° C/W @ 600 LFM	0.0026 (1.18)



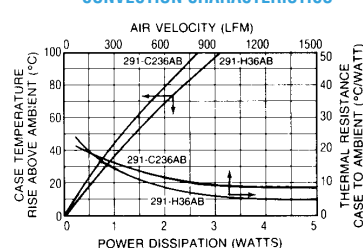
291 SERIES



291-C2



291-H



BOARD LEVEL POWER SEMICONDUCTOR HEAT SINKS



286 SERIES *Aluminum and Copper Low-Cost Wave-Solderable Heat Sinks*
See also 286DB Series on Page 7.

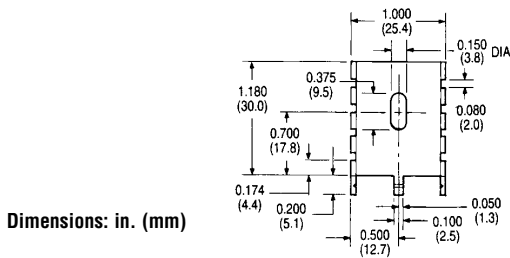
TO-220

Standard P/N	Height Above PC Board in. (mm)	Maximum Footprint in. (mm)	Material	Thermal Performance at Typical Load Natural Convection	Thermal Performance at Typical Load Forced Convection	Weight lbs. (grams)
286-AB ▲	1.190 (30.2)	1.000 (25.4) x 0.500 (12.7)	Aluminum, Anodized	58°C @ 4W	7.4°CW @ 200 LFM	0.0085 (3.86)
286-CBT ▲	1.190 (30.2)	1.000 (25.4) x 0.500 (12.7)	Copper, Black	58°C @ 4W	7.4°CW @ 200 LFM	0.0250 (11.34)
286-CT	1.190 (30.2)	1.000 (25.4) x 0.500 (12.7)	Copper, Tinned	58°C @ 4W	7.4°CW @ 200 LFM	0.0250 (11.34)

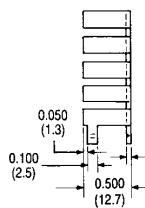
Efficient heat removal at low cost can be achieved by inserting the 286 Series directly into pre-drilled circuit boards; scored mounting tabs may be bent after insertion to provide added stability.

The 286 Series can be wavesoldered directly to the board. Material: 286-AB style (aluminum, black anodized), 286-CBT style (copper, black paint tin tabs), and 286-CT style (copper, tinned).

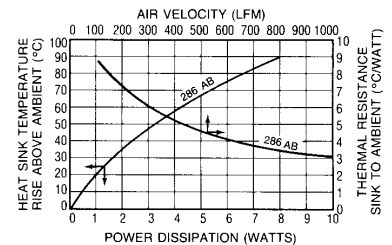
MECHANICAL DIMENSIONS



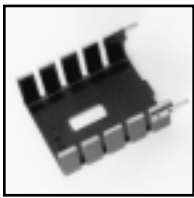
286 SERIES



NATURAL AND FORCED CONVECTION CHARACTERISTICS



Dimensions: in. (mm)



287 SERIES *Wave-Solderable Low-Cost Heat Sinks*

TO-220

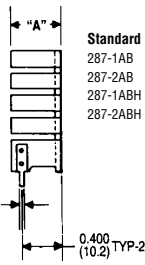
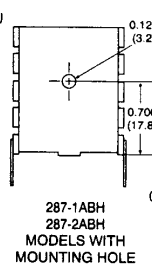
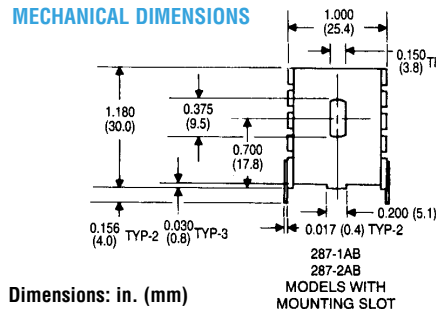
Standard P/N	Height Above PC Board in. (mm)	Maximum Footprint "A" in. (mm)	Thermal Performance at Typical Load Natural Convection	Thermal Performance at Typical Load Forced Convection	Weight lbs. (grams)
287-1AB ▲	1.180 (30.0)	1.000 (25.4) x 0.500 (12.7)	65°C @ 4W	7.8°CW @ 200 LFM	0.0090 (4.08)
287-2AB ▲	1.180 (30.0)	1.000 (25.4) x 1.000 (25.4)	55°10 @ 4W	6.4°CW @ 200 LFM	0.0140 (6.35)

Material: Aluminum, Black Anodized

Mount these cost-effective TO-220 heat sinks vertically into pre-drilled printed circuit boards. Soldered, pre-tinned tabs can be wavesoldered directly to the board. A 0.375 in. (9.5 mm)

mounting slot allows for correct positioning of TO-220 and similar semiconductor packages.

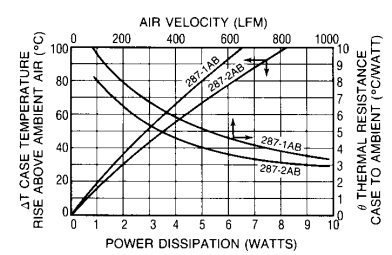
MECHANICAL DIMENSIONS



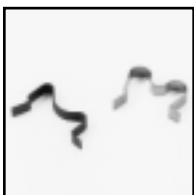
287 SERIES

Standard P/N	Dim. "A"
287-1AB	0.500 (12.7)
287-2AB	1.000 (25.4)
287-1ABH	0.500 (12.7)
287-2ABH	1.000 (25.4)

NATURAL AND FORCED CONVECTION CHARACTERISTICS



Dimensions: in. (mm)



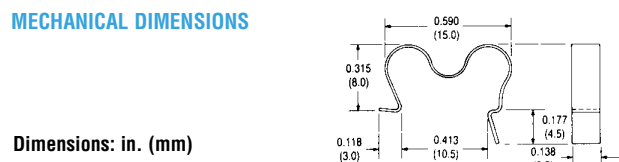
285 AND 330 SERIES *285 SC and 330 SC SpeedClips™*

Standard P/N	Nominal Installed Loading Force	For Use With Series	Material	Weight lbs. (grams)
285 SC	10 lbs	232, 237, 240, 252, 667	Carbon Steel	0.00053 (0.24)
330 SC	4 lbs	232, 237, 240, 252, 667	Stainless Steel	0.00074 (0.34)

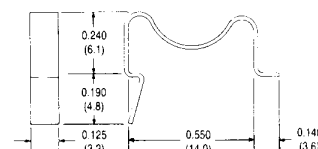
SpeedClips™ employ a locking safety tab for mounting. Must be ordered separately for these heat sink series. Use these SpeedClips™ with our 237, 240, and 252 Series heat sinks for the

lowest production assembly time and cost. Order one SpeedClip™ for each heat sink purchased. Must be purchased with heat sinks.

MECHANICAL DIMENSIONS



Speed Clip 330 SC
4 lb
Nominal Force Installed



Speed Clip 285 SC
10 lb
Nominal Force Installed

Dimensions: in. (mm)

BOARD LEVEL POWER SEMICONDUCTOR HEAT SINKS

260 SERIES **Cup Clips for TO-5 Case Style Semiconductors**

TO-5

Characteristics	TO-5
Thermal Resistance – Epoxy Insulated	14° C/W
Breakdown Voltage – Epoxy Type (VAC), 60 Hz	500
Recommended Operating Voltage, AC or DC	
Clean Conditions: % Hipot Rating	50
Dusty Conditions: % Hipot Rating	30
Dirty Conditions: % Hipot Rating	10 to 20
Temperature Range — Continuous (C°)	-73/+149

Model	Depth of Tapped Base
260-4T5E	0.093 (2.36)
260-4TH5E	0.125 (3.18)

Thread Size:
4 = #4-40 UNC
6 = #6-32 UNC

Mounting Style:
T = tapped
S = stud
P = plain

Base Style: H = hex
Semiconductor Case Style: 5 = TO-5
Insulation: E = epoxy



TO-5 CASE STYLE CUP CLIPS — ORDERING GUIDE

Standard P/N	Insulation Type	Outline Dimension L x W x I.D. in. (mm)	Weight lbs. (grams)	Case Style
260-4T5E ▲	Epoxy Insulated	0.370 (9.4) x 0.380 (9.7) dia. x 0.290 (7.4)	0.0024 (1.09)	TO-5
260-4TH5E ▲	Epoxy Insulated	0.400 (10.2) x 0.370 (9.4) hex. x 0.290 (7.4)	0.0031 (1.41)	TO-5
260-6SH5E ▲	Epoxy Insulated	0.557 (14.1) x 0.370 (9.4) hex. x 0.290 (7.4)	0.0037 (1.68)	TO-5

Materials and Finish: Cups — beryllium copper, black ebolol "C"; Bases — brass, black ebolol "C"

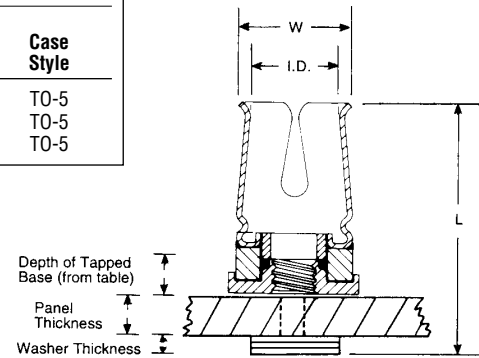
Base Mounting Configurations — TO-5

Plain Type — Epoxy bonded, or used with #4 pan head screws.

Tapped Base — #4-40 UNC screw (not supplied) fits tapped hole. Care should be taken not to use too long a screw, which could short against the semiconductor case. For correct screw lengths:

Correct Screw Length (L) = Depth of Base + Panel Thickness + Washer Thickness

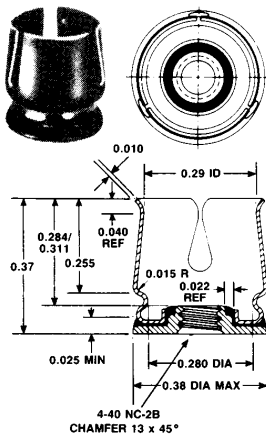
Stud Mounting Base. #6-32 UNC. Nuts and washers not supplied. Stud hole must be slightly countersunk to ensure flat mounting.



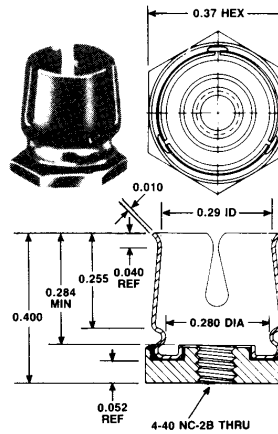
To determine the correct mounting screw lengths, add dimensions as follows:

Correct Screw Length (L) = Depth of Base + Panel Thickness + Washer Thickness

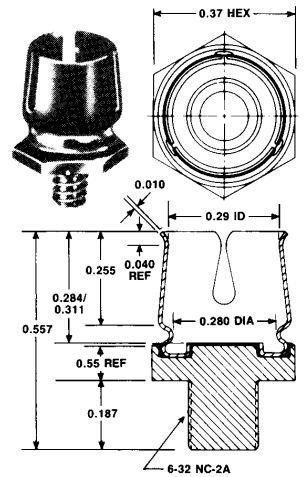
Epoxy Insulated For TO-5



▲ 260-4T5E



▲ 260-4TH5E



260-6SH5E

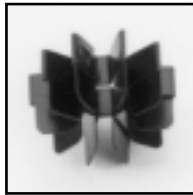
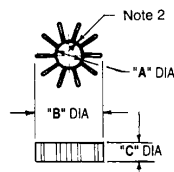
BOARD LEVEL POWER SEMICONDUCTOR HEAT SINKS

200 SERIES

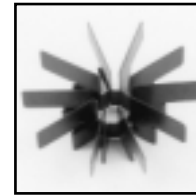
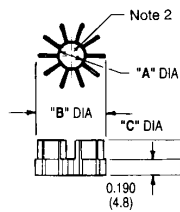
High-Efficiency Heat Sinks for Small Metal Can Power Semiconductors



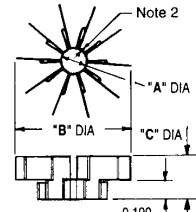
Single-Level Star
201, 202, 204, 205, 211 Series



Dual-Level Star
203, 207, 213 Series



Dual-Level Sunburst
209, 215 Series

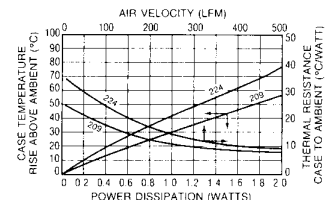
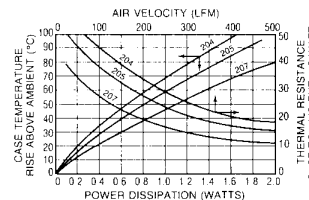
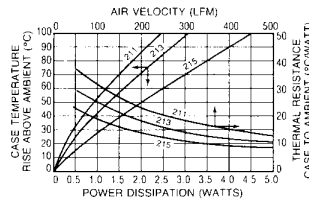
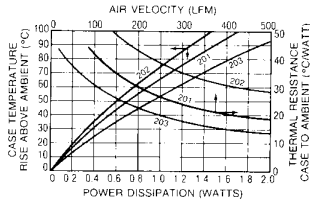


Available Standard P/N & Finish Types	Semiconductor Case Diameter Min/Max in. (mm)	Heat Sink Inside Dia. "A" in. (mm)	Heat Sink Outside Dia. "B" in. (mm)	Heat Sink Height "C" in. (mm)	Natural Convection Case Rise Above Ambient	Forced Convection (CA@200 LFM)	Applicable Power Semiconductor Case Types
201AB	0.161 (4.1)/0.240 (6.1)	0.150 (3.8)	0.640 (16.2)	0.187 (4.8)	65°C @ 1W	31°C/W	TO-18, TO-24, TO-28, TO-40, TO-44
204SB	0.275 (7.0)/0.370 (9.4)	0.255 (6.5)	0.550 (4.8)	0.187 (4.8)	68°C @ 1W	35°C/W	TO-5, TO-9, TO-11, TO-12, TO-26, TO-29, TO-33, TO-43, TO-45
205SB	0.275 (7.0)/0.370 (9.4)	0.255 (6.5)	0.720 (18.3)	0.187 (4.8)	59°C @ 1W	28°C/W	
205AB, 205AP	0.275 (7.0)/0.370 (9.4)	0.255 (6.5)	0.720 (18.3)	0.187 (4.8)	68°C @ 1W	28°C/W	
207SB ▲	0.275 (7.0)/0.370 (9.4)	0.255 (6.5)	0.720 (18.3)	0.375 (9.5)	46°C @ 1W	20°C/W	
207AB ▲, 207AP	0.275 (7.0)/0.370 (9.4)	0.255 (6.5)	0.720 (18.3)	0.375 (9.5)	53°C @ 1W	20°C/W	
209SB	0.275 (7.0)/0.370 (9.4)	0.255 (6.5)	1.280 (32.5)	0.437 (11.1)	30°C @ 1W	13°C/W	
213SB	0.440 (11.2)/0.544 (13.8)	0.420 (10.7)	0.830 (21.1)	0.375 (9.5)	44°C @ 1W	19°C/W	TO-8, TO-38
213AB, 213AP	0.440 (11.2)/0.544 (13.8)	0.420 (10.7)	0.830 (21.1)	0.375 (9.5)	51°C @ 1W	19°C/W	
215AB	0.440 (11.2)/0.544 (13.8)	0.420 (10.7)	1.400 (35.6)	0.437 (11.1)	28°C @ 1W	15°C/W	
215AP	0.440 (11.2)/0.544 (13.8)	0.420 (10.7)	1.400 (35.6)	0.437 (11.1)	32°C @ 1W	15°C/W	

Materials and Finishes Available for 200 Series:

SB	Silver-bearing copper; black ebonol "C"
AB	Aluminum, black anodized
AP	Aluminum, no finish applied

NATURAL AND FORCED CONVECTION CHARACTERISTICS



258 SERIES

Thermal Links for Fused Glass Diodes

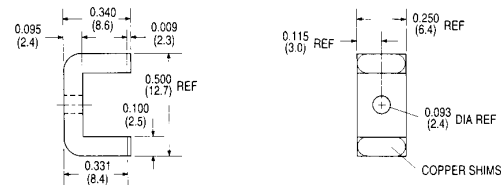
DIODES

Standard P/N	Dimensions in. (mm)	Material	Finish	Weight lbs. (grams)
258 ▲	0.500 (12.7) x 0.250 (6.4) x 0.340 (8.6)	Aluminum	DeltaCoate™ 151 on all surfaces except solder pads and base	0.0018 (0.82)

MECHANICAL DIMENSIONS

258 SERIES

Dimensions: in. (mm)



The thermal resistance from diode leads to chassis or heat sink is 12°C/watt, when unit is mounted with TYPE 120 Joint Compound. If a 10°C/watt chassis or sink to ambient impedance is available, the thermal resistance from the diode leads to ambient is reduced from about 150°C/watt to 22°C/watt.



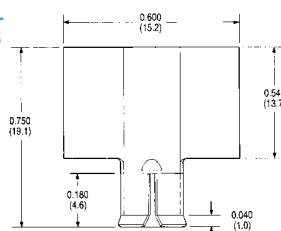
292 SERIES

Heat Sink for Single TO-92

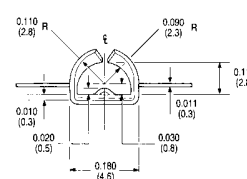
TO-92

Standard P/N	Height Above PC Board in. (mm)	Overall Fin Width in. (mm)	Thermal Performance Natural Convection	Finish	Weight lbs. (grams)
292-AB ▲	0.750 (19.1)	0.600 (15.3)	0.225°C/W @ 0.250 W	Black Anodized	0.00049 (0.22)

MECHANICAL DIMENSIONS

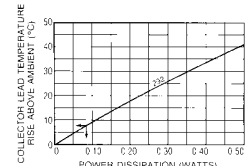


292 SERIES



Dimensions: in. (mm)

NATURAL AND FORCED CONVECTION CHARACTERISTICS



Power semiconductors packaged in a TO-92 style plastic case can be cooled effectively at little additional cost with the addition of the 292-AB heat sink. The 292-AB is effective over the typical power range of such devices. Material: Aluminum, Black Anodized.

BOARD LEVEL POWER SEMICONDUCTOR HEAT SINKS



690 SERIES Highest Efficiency/Lowest Unit Cost Heat Sinks

TO-3, TO-66, TO-220

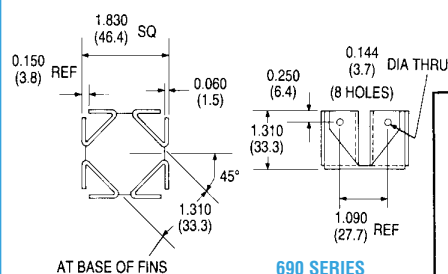
Standard P/N	Height Above PC Board in. (mm)	Outline Dimensions in. (mm)	Thermal Performance at Typical Load		Semiconductor Mounting Hole Pattern	Weight lbs. (grams)
			Natural Convection	Forced Convection		
690-3B ▲	1.310 (33.3)	1.860 (47.2)-sq	44°C @ 7.5W	2.0°C/W @ 400 LFM	(1) TO-3	0.0700 (31.75)
690-66B	1.310 (33.3)	1.860 (47.2)-sq	44°C @ 7.5W	2.0°C/W @ 400 LFM	(1) TO-66	0.0700 (31.75)
690-220B	1.310 (33.3)	1.860 (47.2)-sq	44°C @ 7.5W	2.0°C/W @ 400 LFM	(2) TO-220	0.0700 (31.75)

Material: Aluminum, Black Anodized

These low-cost heat sinks provide the most power dissipation at the lowest unit cost and are available in three standard types to mount and cool one TO-3 or TO-66 metal power semiconductor type or two plastic package TO-220 power semiconductor types. For higher power

semiconductors, the 690 Series can dissipate up to 20 watts while maintaining a mounting surface temperature rise above ambient air temperature of no more than 91°C.

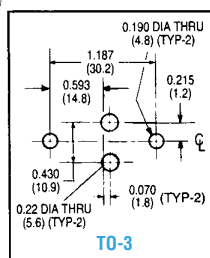
MECHANICAL DIMENSIONS



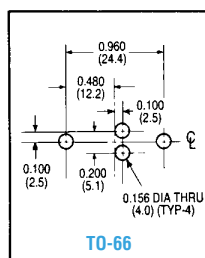
690 SERIES

Dimensions: in. (mm)

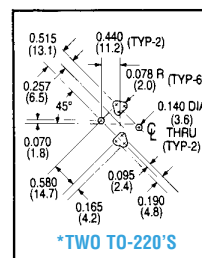
SEMICONDUCTOR MOUNTING HOLES



TO-3

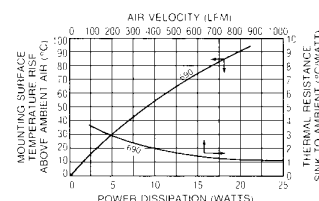


TO-66



*TWO TO-220'S

NATURAL AND FORCED CONVECTION CHARACTERISTICS



635 SERIES Space-Saving Low-Cost Heat Sinks

TO-3

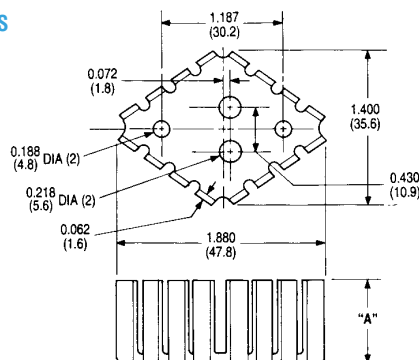
Standard P/N	Height Above PC Board "A" in. (mm)	Outline Dimensions in. (mm)	Thermal Performance at Typical Load		Semiconductor Mounting Hole Pattern	Weight lbs. (grams)
			Natural Convection	Forced Convection		
635-5B2	0.500 (12.7)	1.900 (48.3) x 1.420 (36.0)	90°C @ 8.0W	6.0°C/W @ 300 LFM	TO-3	0.0200 (9.07)
635-75B2	0.750 (19.1)	1.900 (48.3) x 1.420 (36.0)	77°C @ 8.0W	4.8°C/W @ 300 LFM	TO-3	0.0220 (9.98)
635-10B2	1.000 (25.4)	1.900 (48.3) x 1.420 (36.0)	61°C @ 8.0W	3.6°C/W @ 300 LFM	TO-3	0.024 (10.89)
635-125B2	1.250 (31.8)	1.900 (48.3) x 1.420 (36.0)	53°C @ 8.0W	3.1°C/W @ 300 LFM	TO-3	0.028 (12.70)

Material: Aluminum Alloy, Black Anodized

Use this low-cost TO-3 heat sink style for multiple TO-3 applications on a single printed circuit board, where two or more TO-3s must be placed in proximity and minimum space is

available for heat sinking. Four different heights are available, all with TO-3 mounting hole pattern in the base. Consult factory for TO-66, TO-220, and multilead IC hole patterns.

MECHANICAL DIMENSIONS



635 SERIES

Dimensions: in. (mm)

NATURAL AND FORCED CONVECTION CHARACTERISTICS

